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JBC150F594-Q170-B		Features
		<ul style="list-style-type: none"> ● Intel LGA 1151 Core i3/i5/i7 Processors ● 2* SO-DIMM DDR4 2133MHz up to 32GB ● 1* HDMI, 1* DP, 1* DVI-D, 2* RJ45, 6* USB3.0, 2*USB2.0, 2* COM, Onboard TPM (option) ● M/B Form Factor : Mini ITX (170x170mm) ● AC 90~240V_200W FLEX PSU
Processor	Intel LGA 1151 Core i3/i5/i7 Processors	Front I/O
Chipset	Intel Q170 chipset	1* Power LED, 1* HDD LED
Memory	2* SO-DIMM DDR4 2133MHz up to 32GB	Rear I/O
Ethernet	1* Intel i211AT & 1* Intel i219LM GbE	1* HDMI, 1* DVI-D, 2* RJ45, 6* USB3.0,
Display Output	1* HDMI, 1* DP, 1* DVI-D	2* COM, 1* Line in, 1* Line out, 1* MIC, 1* Power SW,
Storage	Support 1 * 3.5" Device or 2 * 2.5" Device	1* Reset SW, 1* Power LED, 1* HDD LED, 1* AC in
Expansion Slot	1* PCI Express x16	Power
	2* Mini PCI Express (full size shared)	90V~240V AC Power in, 200W FLEX PSU inside
		Temperature
		Operating : 0°C~50°C, Storage: -10°C~70°C
		Material Structure
		1U Steel plane integration structure
		Dimension
		430(W) x 250(D) x 44(H) mm

JBC150F596-3160-B		Features
		<ul style="list-style-type: none"> ● Intel Braswell-M N3160 Processor ● 1* SO-DIMM DDR3L 1600MHz up to 8GB ● 1* HDMI, 1* DVI-D, 2* RJ45, 4* USB3.0, 2* USB2.0, 2* COM ● M/B Form Factor : Mini ITX (170x170mm) ● AC 90~240V_200W FLEX PSU
Processor	Intel Braswell-M N3160 Processor	Front I/O
Chipset	SoC	1* Power LED, 1* HDD LED
Memory	1* SO-DIMM DDR3L 1600MHz up to 8GB	Rear I/O
Ethernet	2* Realtek RTL8111G GbE	1* HDMI, 1* DVI-D, 2* RJ45, 4* USB3.0, 2* COM, 1*
Display Output	1* HDMI, 1* DVI-D	Line out, 1* MIC, 1* Power SW, 1* Reset SW, 1* Power
Storage	Support 1 * 3.5" Device or 2* 2.5" Device	LED, 1* HDD LED, 1* AC in
Expansion Slot	1 * PCI Express x1	Power
	1 * Mini PCI Express (full size)	90V~240V AC Power in, 200W FLEX PSU inside
		Temperature
		Operating : 0°C~50°C, Storage: -10°C~70°C
		Material Structure
		1U Steel plane integration structure
		Dimension
		430(W) x 250(D) x 44(H) mm

JBC150F792-3160-B		Features
		<ul style="list-style-type: none"> ● Intel Braswell-M N3160 Processor ● 2* SO-DIMM DDR3L 1600MHz up to 8GB ● 1* HDMI, 1* VGA, 2* RJ45, 3* USB3.0, 3* USB2.0, 2* COM, 1* LPT ● M/B Form Factor : Mini ITX (170x170mm) ● AC 90~240V_200W FLEX PSU
Processor	Intel Braswell-M N3160 Processor	Front I/O
Chipset	SoC	1* Power LED, 1* HDD LED
Memory	2* SO-DIMM DDR3L 1600MHz up to 8GB	Rear I/O
Ethernet	2 * Realtek RTL8111H GbE	1* HDMI, 1* VGA, 2* RJ45, 3* USB3.0, 1* USB2.0,
Display Output	1* HDMI, 1* VGA	2* COM, 1* LPT, 1* Line in, 1* Line out, 1* MIC, 1* Power
Storage	Support 1 * 3.5" Device or 1 * 2.5" Device	SW, 1* Reset SW, 1* Power LED, 1* HDD LED, 1* AC in
Expansion Slot	1* PCI Express x1, 1* Mini PCI Express (full size)	Power
	1* SIM Card Slot	90V~240V AC Power in, 200W FLEX PSU inside"
		Temperature
		Operating : 0°C~50°C, Storage: -10°C~70°C
		Material Structure
		1U Steel plane integration structure
		Dimension
		430(W) x 250(D) x 44(H) mm

JBC150F693-H110-B		Features
		<ul style="list-style-type: none"> ● Intel LGA 1151 Core i3/i5/i7 Processors ● 2* SO-DIMM DDR4 2133MHz up to 32GB ● 1* HDMI, 1* DP, 2* RJ45, 4* USB3.0, 2* USB2.0, 4* COM, Onboard TPM (option) ● M/B Form Factor : Mini ITX (170x170mm) ● AC 90~240V_200W FLEX PSU
Processor	Intel LGA 1151 Core i3/i5/i7 Processors	Front I/O
Chipset	Intel H110 chipset	1* Power LED, 1* HDD LED
Memory	2* SO-DIMM DDR4 2133MHz up to 32GB	Rear I/O
Ethernet	2 * Realtek RTL8111G GbE	1* HDMI, 1* DP, 2* RJ45, 4* USB3.0, 4* COM, 1* Line
Display Output	1* HDMI, 1* DP	in, 1* Line out, 1* MIC, 1* Power SW, 1* Reset SW,
Storage	Support 1 * 3.5" Device or 2 * 2.5" Device	1* Power LED, 1* HDD LED, 1* AC in
Expansion Slot	1* PCI Express x16, 1* Mini PCI Express (full size)	Power
	1* SIM Card Slot	90V~240V AC Power in, 200W FLEX PSU inside
		Temperature
		Operating : 0°C~50°C, Storage: -10°C~70°C
		Material Structure
		1U Steel plane integration structure
		Dimension
		430(W) x 250(D) x 44(H) mm

JBC150F697-Q170-B



Processor	Intel LGA 1151 Core i3/i5/i7 Processors
Chipset	Intel Q170 chipset
Memory	2* SO-DIMM DDR4 2133MHz up to 32GB
Ethernet	1* Intel i211AT & 1* Intel i219LM GbE
Display Output	1* HDMI, 2* DP
Storage	Support 1 * 3.5" Device or 2 * 2.5" Device
Expansion Slot	1* PCI Express x4, 1* Mini PCI Express (full size) 1* SIM Card Slot

Features

- Intel LGA 1151 Core i3/i5/i7 Processors
- 2* SO-DIMM DDR4 2133MHz up to 32GB
- 1* HDMI, 2* DP, 2* RJ45, 4* USB3.0, 2* COM, Onboard TPM (option)
- M/B Form Factor : Mini ITX (170x170mm)
- AC 90~240V_200W FLEX PSU

Front I/O	2* USB 2.0, 1* Power Button, 1* Reset Button 1* Power LED, 1* HDD LED
Rear I/O	1* HDMI, 2* DP, 2* RJ45, 4* USB3.0, 2* COM, 1* Line in, 1* Line out, 1* MIC, 1* Power SW, 1* Reset SW, 1* Power LED, 1* HDD LED, 1* AC in
Power	90V~240V AC Power in, 200W FLEX Power inside
Temperature	Operating : 0°C~50°C, Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 250(D) x 44(H) mm

JBC150F9N-2930-B



Processor	Intel BayTrail-M N2930 Processor
Chipset	SoC
Memory	2* SO-DIMM DDR3L 1333MHz up to 8GB
Ethernet	1* Intel 82574L GbE
Display Output	1* VGA, 1* HDMI
Storage	Support 1 * 3.5" Device or 2 * 2.5" Device
Expansion Slot	1* PCI Express x1 1* Mini PCI Express (full size)

Features

- Intel LGA 1151 Core i3/i5/i7 Processors
- 2* SO-DIMM DDR4 2133MHz up to 32GB
- 1* HDMI, 1* DP, 1* DVI-D, 2* RJ45, 6* USB3.0, 2* USB2.0, 2* COM, Onboard TPM (option)
- M/B Form Factor : Mini ITX (170x170mm)
- AC 90~240V_200W FLEX PSU

Front I/O	2* USB 2.0, 1* Power Button, 1* Reset Button 1* Power LED, 1* HDD LED
Rear I/O	1* HDMI, 1* VGA, 1* RJ45, 1* USB3.0, 3* USB2.0, 1* COM, 1* Line out, 2* PS/2, 1* Power SW, 1* Reset SW, 1* Power LED, 1* HDD LED, 1* AC in
Power	90V~240V AC Power in, 200W FLEX PSU inside
Temperature	Operating : 0°C~50°C, Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 250(D) x 44(H) mm

JBC150F9N-2930BE



Processor	Intel LGA 1151 Core i3/i5/i7 Processors
Chipset	Intel Q170 chipset
Memory	2* SO-DIMM DDR4 2133MHz up to 32GB
Ethernet	1* Intel i211AT & 1* Intel i219LM GbE
Display Output	1* HDMI, 1* DP, 1* DVI-D
Storage	Support 1 * 3.5" Device or 2 * 2.5" Device
Expansion Slot	1* PCI Express x16 2* Mini PCI Express (full size shared)

Features

- Intel LGA 1151 Core i3/i5/i7 Processors
- 2* SO-DIMM DDR4 2133MHz up to 32GB
- 1* HDMI, 1* DP, 1* DVI-D, 2* RJ45, 6* USB3.0, 2* USB2.0, 2* COM, Onboard TPM (option)
- M/B Form Factor : Mini ITX (170x170mm)
- AC 90~240V_200W FLEX PSU

Front I/O	2* USB 2.0, 1* Power Button, 1* Reset Button 1* Power LED, 1* HDD LED
Rear I/O	1* HDMI, 1* DVI-D, 1* DP, 2* RJ45, 6* USB3.0, 2* COM, 1* Line in, 1* Line out, 1* MIC, 1* Power SW, 1* Reset SW, 1* Power LED, 1* HDD LED, 1* AC in
Power	90V~240V AC Power in, 200W FLEX PSU inside
Temperature	Operating : 0°C~50°C, Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 250(D) x 44(H) mm

JBC150F592-Q170-B





Processor	Intel LGA 1151 Core i3/i5/i7 Processors
Chipset	Intel Q170 chipset
Memory	2* SO-DIMM DDR3L 1333MHz up to 16GB
Ethernet	7* Intel i211AT & 1* i219LM GbE
Display Output	1* HDMI
Storage	Support 1 * 3.5" Device or 2 * 2.5" Device
Expansion Slot	1* PCI Express x4, 1* Mini PCI Express (full size) 1* SIM Card Slot


Features


- Intel LGA 1151 Core i3/i5/i7 Processors
- 2* SO-DIMM DDR3L 1333MHz up to 16GB
- 1* HDMI, 8* RJ45, 2* USB3.0, 2* USB2.0, 1* COM (RJ-45 type), Onboard TPM (option)
- M/B Form Factor : Thin Mini ITX (170x170mm)
- AC 90~240V_200W FLEX PSU

Front I/O	2* USB 2.0, 1* Power Button, 1* Reset Button 1* Power LED, 1* HDD LED
Rear I/O	1* HDMI, 8* RJ45, 2* USB3.0, 1* COM (RJ-45 type), 1* GPIO (option), 1* Power SW, 1* Reset SW, 1* Power LED, 1* HDD LED, 1* AC in
Power	90V~240V AC Power in, 200W FLEX PSU inside
Temperature	Operating : 0°C~50°C, Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 250(D) x 44(H) mm

JBC152F53316-19G-B(POE)		Features
		<ul style="list-style-type: none"> ● Intel BayTrail-D J1900 Processor ● On board 4GB DDR3L 1333MHz ● 1* VGA, 4* RJ45, 16* 1000M POE LAN, 1* USB3.0, 1* USB2.0, 2* COM ● M/B Form Factor : 3.5" (148x102mm) ● 400W AC-DC OP Power inside / DC12V-3A & 52V-7A ● AC 90~240V input
Processor	Intel BayTrail-D J1900 Processor	Front I/O
Chipset	SoC	16* 1000M POE LAN
Memory	On board 4GB DDR3L 1333MHz	Rear I/O
Ethernet	16* 1000M POE LAN, 4* Intel i211AT GbE	1* VGA, 4* RJ45, 1* USB2.0, 1* USB3.0, 2* COM, 1* AC ON-OFF, 1* AC-in
Display Output	1* VGA	Power
Storage	Support 1 * 2.5" Device	90V~240V AC Power in
Expansion Slot	1* Mini PCI Express (full size)	400W OP Power inside
		Temperature
		Operating : 0°C~50°C, Storage: -10°C~70°C
		Material Structure
		1U Steel plane integration structure
		Dimension
		430(W) x 252(D) x 44(H) mm

HBJC152F541F-19G-B(PoE)		Features
		<ul style="list-style-type: none"> ● Intel BayTrail-D J1900 Processor ● 1* SO-DIMM DDR3L 1333MHz up to 8GB ● 1* HDMI, 1* VGA, 2* RJ45 , 12* 1000M POE LAN, 4* SFP, 1* USB3.0, 3* USB2.0, 1* COM , 1* Mic , 1* Line out ● Cableless & Expandable Design ● M/B Form Factor : 100x166mm ● DC-12V_5A_60W Adapter
Processor	Intel BayTrail-D J1900 Processor	Front I/O
Chipset	SoC	1* Power Button + LED, 4* SFP (10 GbE), 12* 1000M POE LAN
Memory	1* SO-DIMM DDR3L 1333MHz up to 8GB	Rear I/O
Ethernet	4* SFP (10 GbE), 12* 1000M POE LAN, 2* Intel GbE	1* HDMI, 1* VGA, 2* RJ45 , 1* USB3.0, 3* USB2.0, 1* COM , 1* Mic , 1* Line out
Display Output	1* VGA, 1* HDMI	Power
Storage	USB Device	90V~240V AC Power in, 400W OP Power inside
Expansion Slot	N.C	Temperature
		Operating : 0°C~50°C, Storage: -10°C~70°C
		Material Structure
		1U Steel plane integration structure
		Dimension
		430(W) x 252(D) x 44(H) mm

JBC153F9HB-2930-B		Features
		<ul style="list-style-type: none"> ● Intel BayTrail-M N2930 Processor ● 2* SO-DIMM DDR3L 1333MHz up to 8GB ● 1* VGA, 2* RJ45, 1 pair ByPass GbE ● 1* USB3.0, 1* USB2.0, 2* COM, 1* GPIO ● M/B Form Factor : Thin Mini ITX (170x170mm) ● AC 90~240V_200W FLEX PSU
Processor	Intel BayTrail-M N2930 Processor	Front I/O
Chipset	SoC	1* Power LED, 1* HDD LED, 1* USB 3.0, 1* USB 2.0, 2* COM, 1* GPIO, 1* VGA, 2* RJ45, 1 pair ByPass GbE
Memory	2* SO-DIMM DDR3L 1333MHz up to 8GB	Rear I/O
Ethernet	2* Intel i211AT GbE	1* AC ON-OFF, 1* AC-in
	2* Intel i211AT GbE (Support 1 pair Bypass LAN)	Power
Display Output	1* VGA	90V~240V AC Power in
Storage	Support 2 * 2.5" Device	200W FLEX Power inside
Expansion Slot	1* Mini PCI Express (full size)	Temperature
		Operating : 0°C~50°C
		Storage: -10°C~70°C
		Material Structure
		1U Steel plane integration structure
		Dimension
		430(W) x 251(D) x 44(H) mm

JBC153F9HB-2930-G4		Features
		<ul style="list-style-type: none"> ● Intel BayTrail-M N2930 Processor ● 2* SO-DIMM DDR3L 1333MHz up to 8GB ● 1* VGA, 6* RJ45, 1 pair ByPass GbE, 1* USB3.0, 1* USB2.0, 2* COM, 1* GPIO ● M/B Form Factor : Thin Mini ITX (170x170mm) ● AC 90~240V_200W FLEX PSU
Processor	Intel BayTrail-M N2930 Processor	Front I/O
Chipset	SoC	1* Power LED, 1* HDD LED, 1* USB 3.0, 1* USB 2.0, 2* COM, 1* GPIO, 1* VGA, 6* RJ45, 1 pair ByPass GbE
Memory	2* SO-DIMM DDR3L 1333MHz up to 8GB	Rear I/O
Ethernet	6* Intel i211AT GbE	1* AC ON-OFF, 1* AC-in
	2* Intel i211AT GbE (Support 1 pair Bypass LAN)	Power
Display Output	1* VGA	90V~240V AC Power in
Storage	Support 2 * 2.5" Device	200W FLEX Power inside
Expansion Slot	1* Mini PCI Express (full size)	Temperature
		Operating : 0°C~50°C
		Storage: -10°C~70°C
		Material Structure
		1U Steel plane integration structure
		Dimension
		430(W) x 251(D) x 44(H) mm

JBC153F9HB-2930-B4



Processor	Intel BayTrail-M N2930 Processor
Chipset	SoC
Memory	2* SO-DIMM DDR3L 1333MHz up to 8GB
Ethernet	2* Intel i211AT GbE
	6* Intel i211AT GbE (Support 3 pairs Bypass LAN)
Display Output	1* VGA
Storage	Support 2 * 2.5" Device
Expansion Slot	1* Mini PCI Express (full size)

Features

- Intel BayTrail-M N2930 Processor
- 2* SO-DIMM DDR3L 1333MHz up to 8GB
- 1* VGA, 2* RJ45, 3 pairs ByPass GbE, 1* USB3.0, 1* USB2.0, 2* COM, 1* GPIO
- M/B Form Factor : Thin Mini ITX (170x170mm)
- AC 90~240V_200W FLEX PSU

Front I/O	1* Power LED, 1* HDD LED, 1* USB 3.0, 1* USB 2.0, 2* COM, 1* GPIO, 1* VGA, 2* RJ45, 3 pairs ByPass GbE
Rear I/O	1* AC ON-OFF, 1* AC-in
Power	90V~240V AC Power in 200W FLEX Power inside
Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 251(D) x 44(H) mm

JBC153F9HG-2930-B4



Processor	Intel BayTrail-M N2930 Processor
Chipset	SoC
Memory	2* SO-DIMM DDR3L 1333MHz up to 8GB
Ethernet	4* Intel i211AT GbE
	4* Intel i211AT GbE (Support 2 pairs Bypass LAN)
Display Output	1* VGA
Storage	Support 2 * 2.5" Device
Expansion Slot	1* Mini PCI Express (full size)

Features

- Intel BayTrail-M N2930 Processor
- 2* SO-DIMM DDR3L 1333MHz up to 8GB
- 1* VGA, 4* RJ45, 2 pairs ByPass GbE, 1* USB3.0, 1* USB2.0, 2* COM, 1* GPIO
- M/B Form Factor : Thin Mini ITX (170x170mm)
- AC 90~240V_200W FLEX PSU

Front I/O	1* Power LED, 1* HDD LED, 1* USB 3.0, 1* USB 2.0, 2* COM, 1* GPIO, 1* VGA, 4* RJ45, 2 pairs ByPass GbE
Rear I/O	1* AC ON-OFF, 1* AC-in
Power	90V~240V AC Power in 200W FLEX Power inside
Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 251(D) x 44(H) mm

JBC153F9HG-2930-B



Processor	Intel BayTrail-M N2930 Processor
Chipset	SoC
Memory	2* SO-DIMM DDR3L 1333MHz up to 8GB
Ethernet	4* Intel i211AT GbE
Display Output	1* VGA
Storage	Support 2 * 2.5" Device
Expansion Slot	1* Mini PCI Express (full size)

Features

- Intel BayTrail-M N2930 Processor
- 2* SO-DIMM DDR3L 1333MHz up to 8GB
- 1* VGA, 4* RJ45, 1* USB3.0, 1* USB2.0, 2* COM, 1* GPIO
- M/B Form Factor : Thin Mini ITX (170x170mm)
- AC 90~240V_200W FLEX PSU

Front I/O	1* Power LED, 1* HDD LED, 1* USB 3.0, 1* USB 2.0, 2* COM, 1* GPIO, 1* VGA, 4* RJ45
Rear I/O	1* AC ON-OFF, 1* AC-in
Power	90V~240V AC Power in 200W FLEX Power inside
Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 251(D) x 44(H) mm

JBC153F9HG-2930-G4





Processor	Intel BayTrail-M N2930 Processor
Chipset	SoC
Memory	2* SO-DIMM DDR3L 1333MHz up to 8GB
Ethernet	8* Intel i211AT GbE
Display Output	1* VGA
Storage	Support 2 * 2.5" Device
Expansion Slot	1* Mini PCI Express (full size)


Features


- Intel BayTrail-M N2930 Processor
- 2* SO-DIMM DDR3L 1333MHz up to 8GB
- 1* VGA, 8* RJ45, 1* USB3.0, 1* USB2.0, 2* COM, 1* GPIO
- M/B Form Factor : Thin Mini ITX (170x170mm)
- AC 90~240V_200W FLEX PSU

Front I/O	1* Power LED, 1* HDD LED, 1* USB 3.0, 1* USB 2.0, 2* COM, 1* GPIO, 1* VGA, 8* RJ45
Rear I/O	1* AC ON-OFF, 1* AC-in
Power	90V~240V AC Power in 200W FLEX Power inside
Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 251(D) x 44(H) mm

JBC153F592-Q170-B		Features	
		<ul style="list-style-type: none"> • Intel LGA 1151 Core i3/i5/i7 Processors • 2* SO-DIMM DDR3L 1333MHz up to 16GB • 1* HDMI, 8* RJ45, 2* USB3.0, 1* COM (RJ-45 type), Onboard TPM (option) • M/B Form Factor : Thin Mini ITX (170x170mm) • AC 90~240V_200W FLEX PSU 	
Processor	Intel LGA 1151 Core i7/i5/i3/Pentium Processor	Front I/O	1* Power LED, 1* HDD LED, 2* USB 3.0, 1* GPIO, 1* COM (RJ45 type), 1* HDMI, 8* RJ45
Chipset	Intel Q170 chipset	Rear I/O	1* AC ON-OFF, 1* AC-in
Memory	2* SO-DIMM DDR3L 1333MHz up to 16GB	Power	90V~240V AC Power in 200W FLEX Power inside
Ethernet	7* Intel i211AT & 1* i219LM GbE	Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Display Output	1* HDMI	Material Structure	1U Steel plane integration structure
Storage	Support 2 * 2.5" Device	Dimension	430(W) x 251(D) x 44(H) mm
Expansion Slot	1* PCI Express x4, 1* Mini PCI Express (full size) 1* SIM Card Slot		

JBC153F592-Q170-G4		Features	
		<ul style="list-style-type: none"> • Intel LGA 1151 Core i3/i5/i7 Processors • 2* SO-DIMM DDR3L 1333MHz up to 16GB • 1* HDMI, 12* RJ45, 2* USB3.0, 1* COM (RJ-45 type), Onboard TPM (option) • M/B Form Factor : Thin Mini ITX (170x170mm) • AC 90~240V_200W FLEX PSU 	
Processor	Intel LGA 1151 Core i7/i5/i3/Pentium Processor	Front I/O	1* Power LED, 1* HDD LED, 2* USB 3.0, 1* GPIO, 1* COM (RJ45 type), 1* HDMI, 12* RJ45
Chipset	Intel Q170 chipset	Rear I/O	1* AC ON-OFF, 1* AC-in
Memory	2* SO-DIMM DDR3L 1333MHz up to 16GB	Power	90V~240V AC Power in 200W FLEX Power inside
Ethernet	11* Intel i211AT & 1* i219LM GbE	Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Display Output	1* HDMI	Material Structure	1U Steel plane integration structure
Storage	Support 2 * 2.5" Device	Dimension	430(W) x 251(D) x 44(H) mm
Expansion Slot	1* PCI Express x4, 1* Mini PCI Express (full size) 1* SIM Card Slot		

JBC153F592-Q170-B4		Features	
		<ul style="list-style-type: none"> • Intel LGA 1151 Core i3/i5/i7 Processors • 2* SO-DIMM DDR3L 1333MHz up to 16GB • 1* HDMI, 8* RJ45, 2 pairs ByPass GbE, 2* USB3.0, 1* COM (RJ-45 type), Onboard TPM (option) • M/B Form Factor : Thin Mini ITX (170x170mm) • AC 90~240V_200W FLEX PSU 	
Processor	Intel LGA 1151 Core i7/i5/i3/Pentium Processor	Front I/O	1* Power LED, 1* HDD LED, 2* USB 3.0, 1* GPIO, 1* COM (RJ45 type), 1* HDMI, 8* RJ45, 2 pairs ByPass GbE
Chipset	Intel Q170 chipset	Rear I/O	1* AC ON-OFF, 1* AC-in
Memory	2* SO-DIMM DDR3L 1333MHz up to 16GB	Power	90V~240V AC Power in 200W FLEX Power inside
Ethernet	7* Intel i211AT & 1* i219LM GbE	Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Display Output	4* Intel i211AT GbE (Support 2 pairs ByPass LAN)	Material Structure	1U Steel plane integration structure
Storage	Support 2 * 2.5" Device	Dimension	430(W) x 251(D) x 44(H) mm
Expansion Slot	1* PCI Express x4, 1* Mini PCI Express (full size) 1* SIM Card Slot		

JBC160F699-3758-S		Features	
		<ul style="list-style-type: none"> • Intel Denverton C3758 Processors • 4* 288-pin UDIMM/RDIMM up to 64/128GB DDR4 2133MHz SDRAM • 1* VGA, 2* RJ45, 4* 10GbE SFP+, 3* USB3.0, 2* USB2.0, 1* COM • M/B Form Factor : Mini ITX (170x170mm) • AC 90~240V_300W FLEX PSU 	
Processor	Denverton C3758 Processor	Front I/O	2* USB 2.0, 1* Power Button, 1* Reset Button 1* Power LED, 1* HDD LED"
Chipset	SoC	Rear I/O	2* RJ45, 4* 10G SFP, 3* USB3.0, 1* AC in
Memory	4* 288-pin UDIMM/RDIMM with ECC DDR4 2133MHz up to 64/128GB	Power	90V~240V AC Power in 300W FLEX Power inside
Ethernet	2* Intel GbE, 4* 10GbE SFP+	Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Display Output	1* VGA	Material Structure	1U Steel plane integration structure
Storage	Support 4* 3.5" Device, Support 1* M.2 Device	Dimension	430(W) x 467(D) x 44(H) mm
Expansion Slot	1* PCI Express x8 (PCIe x16 slot) 2* Mini PCI Express (full & half size)		

HBJC160F795-Q170-S



Processor	Intel LGA 1151 Core i7/i5/i3/Pentium Processor
Chipset	Intel Q170 chipset
Memory	2 * DDR4 SODIMM Up to 32 GB
Ethernet	4 * Intel Gigabit LAN (1 * i219LM, 3 * i211AT)
Display Output	1* HDMI
Storage	Support 4* 3.5" Device, Support 1* MSATA Device
Expansion Slot	1* M.2-2230 (E KEY), 1* Mini PCI Express (half size), 1* Mini PCI Express (full size) for MSATA

Features

- Intel LGA 1151 Core i3/i5/i7 Processors
- 2* DDR4 SODIMM Up to 32 GB
- 2* USB2.0, 4* USB3.0 , 1* HDMI, 4* RJ45 , 1*COM(RJ45 TYPE) , 1* GPIO , 1* 2.5" DRIVE
- M/B Form Factor : Mini ITX (170x170mm)
- AC 90~240V_300W FLEX PSU

Front I/O	2* USB 2.0, 1* Power Button, 1* Reset Button, 1* Power LED, 1* HDD LED
Rear I/O	2* RJ45, 4* USB3.0 , 1* HDMI, 4 * RJ45, 1*COM(RJ45 TYPE) , 1* GPIO , 1* AC in
Power	90V~240V AC Power in 300W FLEX Power inside
Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 467(D) x 44(H) mm

HBJC160F796-Q370-S



Processor	Intel LGA 1151 Core i7/i5/i3/Pentium Processor
Chipset	Intel Q370 chipset
Memory	2* 260-pin SO-DIMM DDR4 2400MHz up to 32GB
Ethernet	1* Intel i211AT & 1* i219LM GbE
Display Output	1* HDMI, 1* DP, 1*VGA
Storage	Support 4* 3.5" Device
Expansion Slot	Support 1* M.2 Device(M Key, 2242/2260/2280) 1* PCIe x16, 1* Mini PCIe (half size)

Features

- Intel Core i7/i5/i3/ Pentium / Celeron desktop processor
- 2* 260-pin SO-DIMM up to 32GB DDR4 2400MHz SDRAM (ECC for C246 only)
- 1* HDMI, 1* DP, 1* VGA , 4* USB3.1, 6* USB3.0, 2* USB2.0
- M/B Form Factor : Mini ITX (170x170mm)
- AC 90~240V_300W FLEX PSU

Front I/O	2* USB 2.0, 1* Power Button, 1* Reset Button 1* Power LED, 1* HDD LED"
Rear I/O	1* HDMI, 1* DP, 1*VGA , 4* USB3.1, 2* USB3.0, 2* USB2.0 , 2 *COM, 1* MIC, 1* Line-out, 1* Line-in
Power	90V~240V AC Power in 300W FLEX Power inside
Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 467(D) x 44(H) mm

JBC161F594-Q170-S



Processor	Intel LGA 1151 Core i3/i5/i7 Processors
Chipset	Intel Q170 chipset
Memory	2* SO-DIMM DDR4 2133MHz up to 32GB
Ethernet	1* Intel i211AT & 1* Intel i219LM GbE
Display Output	1* HDMI, 1* DP, 1* DVI-D
Storage	Support 4* 3.5" Device, Support 1* 2.5" Device
Expansion Slot	1* PCI Express x16 2* Mini PCI Express (full size shared)

Features

- Intel LGA 1151 Core i3/i5/i7 Processors
- 2* SO-DIMM DDR4 2133MHz up to 32GB
- 1* HDMI, 1* DP, 1* DVI-D, 2* RJ45, 6* USB3.0, 2* USB2.0, 2* COM, Onboard TPM (option)
- M/B Form Factor : Mini ITX (170x170mm)
- AC 90~240V_300W FLEX PSU

Front I/O	2* USB 2.0, 1* Power Button, 1* Reset Button 1* Power LED, 1* HDD LED
Rear I/O	1* HDMI, 1* DVI-D, 1* DP, 2* RJ45, 6* USB3.0, 2* COM, 1* Line in, 1* Line out, 1* MIC, 1* AC in
Power	90V~240V AC Power in 300W FLEX Power inside
Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 467(D) x 44(H) mm

JBC161F94M-Q87-S



Processor	Intel LGA 1150 Core i3/i5/i7 Processors
Chipset	Intel Q87 chipset
Memory	4* 240-pin UDIMM DDR3 1600MHz up to 32GB
Ethernet	1* Intel i211AT & 1* Intel i217LM GbE
Display Output	1* HDMI, 1* VGA
Storage	Support 4* 3.5" Device, Support 1* 2.5" Device
Expansion Slot	1* PCI Express x16, 1* PCI Express x4, 1* PCI Express x1, 1* Mini PCI Express (full size)

Features

- Intel LGA 1150 Core i3/i5/i7 Processors
- 4* 240-pin UDIMM up to 32GB DDR3 1600MHz SDRAM
- 1* HDMI, 1* VGA, 2* RJ45, 2* USB3.0, 6* USB2.0, 3* COM
- M/B Form Factor : Micro ATX (245x245mm)
- AC 90~240V_300W FLEX PSU

Front I/O	2* USB 2.0, 1* Power Button, 1* Reset Button 1* Power LED, 1* HDD LED
Rear I/O	1* HDMI, 1* VGA, 2* RJ45, 2* USB3.0, 4* USB2.0, 3* COM, 2* PS/2, 1* AC in
Power	90V~240V AC Power in 300W FLEX Power inside
Temperature	Operating : 0°C~50°C Storage: -10°C~70°C
Material Structure	1U Steel plane integration structure
Dimension	430(W) x 467(D) x 44(H) mm

JC165 Caes



JC165 Caes

Dimension(mm)	482(W) x 660(D) x 44.5 mm(H)
Installable	EATX - 12" x 13" (305 x 340 mm)
motherboard	ATX - 12" x 9.6" (216 x 254 mm) Micro ATX - 9.6" x 9.6" (244 x 244 mm) Mini-ITX - 6.7" x 6.7"(170 x 170 mm)
Storage	4 *3.5" Device (HDD Tray design, Hot-swappable)
CD/DVD-ROM	N.C
Power Specifications	1U 300W Flex ATX Power (300W)
System Fan	4 *4028 DC FAN
Expansion slot	1 full height straight slot (requires adapter)
Front I/O	2 *USB2.0, 1 *Power SW, 1 *Reset, 1 *Power LED, 1 *HDD R/W
Shell material	Galvanized sheet, thickness 1.2 mm

JC170 Case



JC170 Case

Dimension(mm)	482(W) x 550(D) x 89 mm(H)
Installable	ATX - 12" x 9.6" (216 x 254 mm)
motherboard	Micro ATX - 9.6" x 9.6" (244 x 244 mm) Mini-ITX - 6.7" x 6.7"(170 x 170 mm)
Storage	8 *3.5" Device + 2 *2.5" Device (HDD Tray design, Hot-swappable)
CD/DVD-ROM	N.C
Power Specifications	1U 300W Flex ATX Power
System Fan	4 *8025 DC FAN
Expansion slot	7 half-height straight slots
Front I/O	2 *USB2.0, 1 *Power SW, 1 *Reset, 1 *Power LED, 1 *HDD R/W
Shell material	Galvanized sheet, thickness 1.2 mm

JC180 Case



JC180 Case

Dimension(mm)	482(W) x 390(D) x 133 mm(H)
Installable	ATX - 12" x 9.6" (216 x 254 mm)
motherboard	Micro ATX - 9.6" x 9.6" (244 x 244 mm) Mini-ITX - 6.7" x 6.7"(170 x 170 mm)
Storage	11 *3.5" Device
CD/DVD-ROM	N.C
Power Specifications	300W ATX Power
System Fan	2 *8025 DC FAN
Expansion slot	5 full height straight slot
Front I/O	2 *USB2.0, 1 *Power SW, 1 *Reset, 1 *Power LED, 1 *HDD R/W
Shell material	Galvanized sheet, thickness 1.0 mm, Black paint

JC190 Caes



JC190 Caes

Dimension(mm)	482(W) x 450(D) x 178 mm(H)
Installable	ATX - 12" x 9.6" (216 x 254 mm)
motherboard	Micro ATX - 9.6" x 9.6" (244 x 244 mm) Mini-ITX - 6.7" x 6.7"(170 x 170 mm)
Storage	8 *3.5" Device + 4 *2.5" Device
CD/DVD-ROM	N.C
Power Specifications	300W ATX Power
System Fan	1 *1225 DC FAN + 2 *8025 DC FAN
Expansion slot	7 full height straight slot
Front I/O	2 *USB2.0, 1 *Power SW, 1 *Reset, 1 *Power LED, 1 *HDD R/W
Shell material	Galvanized sheet, thickness 1.0 mm, White paint